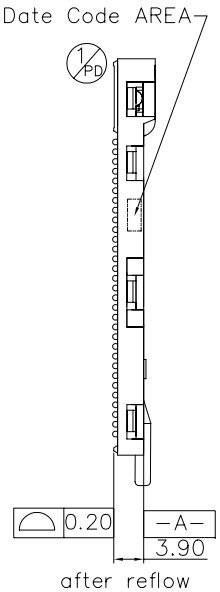
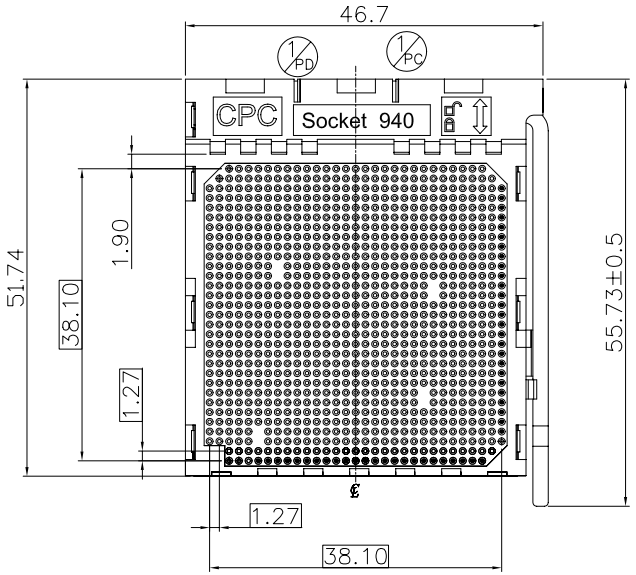
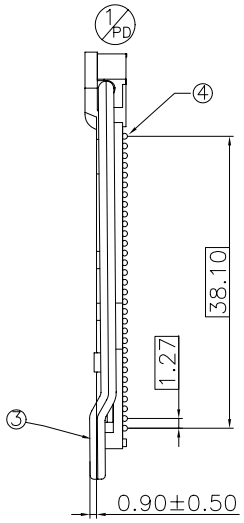
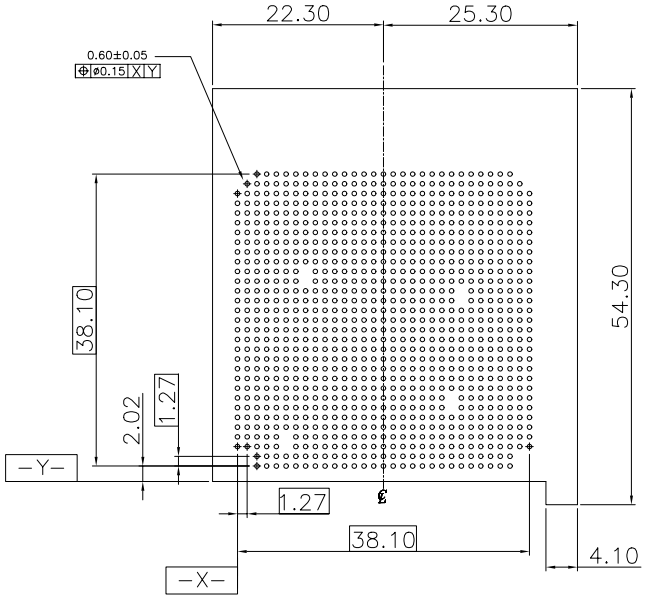
RoHS Compliant 2002/95/EC

Process Capable

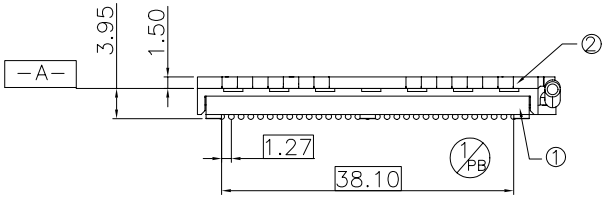








RECOMMENDED P.C BOARD LAYOUT



1. 127089FK940□□00PY
   F

F.Selective plating

J1-05μ"Min.Gold in contact area.

J2-Gold flash in contact area.

J3-10μ"Min.Gold in contact area.

J4-15μ"Min.Gold in contact area.

J5-30μ"Min.Gold in contact area.

PA

NO.	DESCRIPTION	MATERIAL	COLOR	REMARK
5	TERMINAL	Copper Alloy	———	GOLD PLATED OVER Ni
4	Solder Ball	Solder Alloy Composition	———	———
3	HANDLE	Stainless Steel	———	———
2	COVER	High Temp.Plastic	Natural	UL 94V-0
1	BASE	High Temp.Plastic	BLACK	UL 94V-0

ECN(DCN) NO.	REV	DATE	DESCRIPTION	CHANGE	APPRO.	GENERAL TOLERANCE UNLESS OTHERWISE NOTED	
	PD	02/04/07'	修改圖面與實物相符			Angle	±2°
———	PC	05/23/06'	結構變更	吳玉明	范政徽	X.	±0.50
———	PB	12/13/05'	修改標注	吳玉明	范政徽	X.X	±0.25
———	PA	08/31/05'	變更新圖框	吳玉明	范政徽	X.XX	±0.15

DRAW	陳葳葳	07/26/05'
DESIGN	吳玉明	07/26/05'
CHECK	范政徽	07/26/05'
APPRO.	范政徽	07/26/05'

SUYIN CONNECTOR

CUSTOMER COPY	TITLE: Socket 940 Solder Ball Type		
PART NO.	127089FK940JX00PY		
PART NO. (OLD)	———		
FILE NAME.	C ING	127089FK940JX00PY-C	
SCALE 1:1	UNIT:mm	A4	SHEET: 1 of 1

SOCKET DEP

050726-EA012